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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/064,171	06/18/2002	James W. Adkisson	BUR919990299	8362	
30743	7590 02/13/2004		EXAM	EXAMINER	
WHITHAM, CURTIS & CHRISTOFFERSON, P.C.			MAGEE, T	MAGEE, THOMAS J	
11491 SUNS SUITE 340	SET HILLS ROAD		ART UNIT	PAPER NUMBER	
RESTON, V	'A 20190		2811		
			DATE MAIL ED: 02/13/200	DATE MAIL ED: 02/13/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)					
Advisory Action	10/064,171	ADKISSON ET AL.					
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	Thomas J. Magee	2811	AW				
The MAILING DATE of this communication appears on the cover she t with the correspondence addr ss							
THE REPLY FILED 30 December 2003 FAILS TO PLA Therefore, further action by the applicant is required to a final rejection under 37 CFR 1.113 may only be either: (condition for allowance; (2) a timely filed Notice of Appe Examination (RCE) in compliance with 37 CFR 1.114.	avoid abandonment of this application and a timely filed amendment white an armond the street which are the street and a street and a street are street as a street are street are street as a street are stre	cation. A proper replich places the application	ply to a cation in				
PERIOD FOR REPLY [check either a) or b)]							
a) \square The period for reply expires 3 months from the mailing date of the final rejection.							
b) The period for reply expires on: (1) the mailing date of this Advisory Action, or (2) the date set forth in the final rejection, whichever is later. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of the final rejection. ONLY CHECK THIS BOX WHEN THE FIRST REPLY WAS FILED WITHIN TWO MONTHS OF THE FINAL REJECTION. See MPEP 706.07(f).							
Extensions of time may be obtained under 37 CFR 1.136(a). The day have been filed is the date for purposes of determining the period of exter 37 CFR 1.17(a) is calculated from: (1) the expiration date of the shortene (b) above, if checked. Any reply received by the Office later than three meanned patent term adjustment. See 37 CFR 1.704(b).	ision and the corresponding amount of the d statutory period for reply originally set in	e fee. The appropriate ext the final Office action; or	tension fee under (2) as set forth in				
1. A Notice of Appeal was filed on Appellant's Brief must be filed within the period set forth in 37 CFR 1.192(a), or any extension thereof (37 CFR 1.191(d)), to avoid dismissal of the appeal.							
2. The proposed amendment(s) will not be entered by	pecause:						
(a) ⊠ they raise new issues that would require further consideration and/or search (see NOTE below);							
(b) they raise the issue of new matter (see Note below);							
(c) they are not deemed to place the application in better form for appeal by materially reducing or simplifying the issues for appeal; and/or							
(d) they present additional claims without cance NOTE:	ling a corresponding number of	finally rejected clain	ms.				
3. Applicant's reply has overcome the following reje	ction(s):						
4. Newly proposed or amended claim(s) would be allowable if submitted in a separate, timely filed amendment canceling the non-allowable claim(s).							
5. The a) affidavit, b) exhibit, or c) request for reconsideration has been considered but does NOT place the application in condition for allowance because: (See attached sheet).							
6. The affidavit or exhibit will NOT be considered because it is not directed SOLELY to issues which were newly raised by the Examiner in the final rejection.							
7.⊠ For purposes of Appeal, the proposed amendment(s) a)⊠ will not be entered or b)□ will be entered and an explanation of how the new or amended claims would be rejected is provided below or appended.							
The status of the claim(s) is (or will be) as follows:							
Claim(s) allowed:							
Claim(s) objected to:							
Claim(s) rejected: 1-8.							
Claim(s) vithdrawn from consideration: <u>9-17</u> .							
8.⊠ The drawing correction filed on <u>December 30, 21003</u> is a)⊠ approved or b)☐ disapproved by the Examiner.							
9. Note the attached Information Disclosure Statement(s)(PTO-1449) Paper No(s)							
10. Other:							
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Item 2c):

The proposed amendment raises new issues that would require further consideration and/or search.

Thomas Magee

February 6, 2004

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Item 5c):

- 1) Examiner notes that Applicant's comments (p. 13, Response) are based on proposed amendment to change Claim 1, and as such will not be addressed here.
- 2) Applicant alleges (p. 14, Response) that Sung teaches a tungsten "spacer" but does not suggest silicidation. Examiner does not concur. Applicant has quoted another embodiment which was not addressed in the Office Action. Sung clearly teaches the formation of silicide spacers throughout the reference (Figure 3b) (Col. 6, lines 4-5) (Col. 1, lines 61-63) (Col. 2, lines 7-10) (Col. 7, lines 60-61).
- 3) Applicant alleges (p. 14, Response) that Liu et al. do not teach any of the elements not taught by Mizuno et al. Examiner disagrees. Liu et al. disclose a method for forming damascene interconnects (Figure 2F) which is not disclosed by Mizuno et al. Applicant is reminded that one cannot show nonobviousness by attacking references individually where the rejections are based on combinations of references. See *In re Keller*, 642 F.2d 413, 208 USPQ 871 (CCPA 1981); *In re Merck & Co.*, 800 F.2d 1091, 231 USPQ 375 (Fed. Cir. 1986).
- 4) Applicant has continued arguments that the process limitation, "sub-lithographic," constitutes a viable device or structural limitation in terms of dimension. The term, sub-lithographic, is a changing parameter, and is different today from what was defined ten years ago, and even since the instant application was filed in 2002. Further, this is tool dependent, organization dependent, and location dependent. The term is therefore, indefinite with regard to a dimensional description of a structural element in a device application.